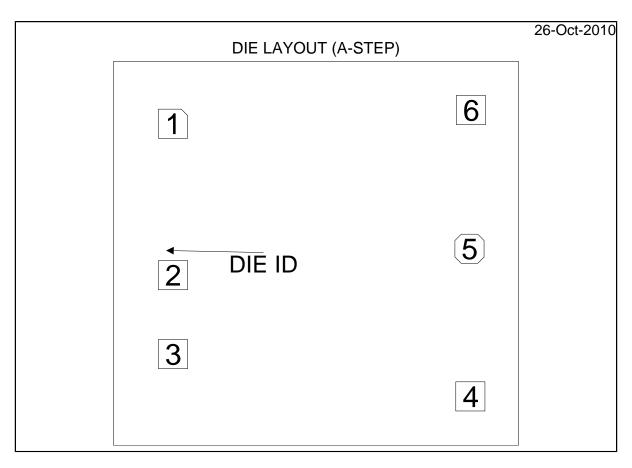


LMP7701 MDA Precision 250uA Vos (25C) Single Op Amp



DIE/WAFER CHARACTERISTICS

DIE/WAFER CHARA	CTERISTICS				
Fabrication Attributes		General Die Information			
Physical Die	LMP7701A	Bond Pad Opening	75.00µm x 75.00µm		
Identification		Size (min)			
Die Step	A	Bond Pad Metalization	AL 0.5%CU		
Physical Attributes		Passivation	PECVDOX NITRIDE		
Wafer Diameter	203.2mm	Back Side Metal	BAREBACK		
Die Size (Drawn)	1041.40µm x 988.06µm	Back Side Connection	Floating		
	41.0mils x 38.9mils				
Thickness	0.0µm Nominal				
Min Pitch	202.95μm				
Note: All values are round	ded to the nearest micron.				
Special Assembly Requir	ements:				



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Χ	Υ	Χ		Υ
OUTPUT	1	-367.90	333.50	75.00	Х	75.0
V-	2	-367.90	-56.25	75.00	Χ	75.0
V+	3	-367.90	-259.20	75.00	Х	75.0
-IN	4	397.20	-368.10	75.00	Х	75.0
NC	5	394.90	11.75	75.00	Х	75.0
+IN	6	398.60	368.65	75.00	Х	75.0



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